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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In regard to the Patent Application of Jiang-Jen Lin and Yi-Chien Chen:

Application No.: 10/039,558 Filing Date: January 8, 2002

Publication No.: US 2003/0134957A1

Publication Date: July 17, 2003

For: COMPLEXES OF CLAY AND POLYOXYALKYLENE AMINE AND METHOD

FOR PRODUCING THE SAME.

Commissioner for Patents Washington, DC 20231

Dear Sir/Madame:

Pursuant to 37 C.F.R. §1.99, the undersigned hereby submits copies of the following publication relevant to the subject published application:

- US 6,096,803 (Aug. 1, 2000)
 Methods of Preparation of Organic-Inorganic Hybrid Nanocomposites.
- 2. US 6,017,632 (Jan. 25,2000)
 Hybrid Organic-Inorganic Nanocomposites and Methods of Preparation.
- 3. US 5,993,769 (Nov. 30, 1999) Homostructured Mixed Organic and Inorganic Cation Exchanged Tapered Compositions.
- US 5,866,645 (Feb. 2, 1999)
 Homostructured Mixed Organic and Inorganic Cation Exchanged Tapered Compositions.
- US 5,853,886 (Dec. 29, 1948)
 Hybrid Nanocomposites Comprising Layered Inorganic Material and Methods of Preparation.
- 6. US 5,801,216 (Sept. 1, 1998) Flexible Resin-Clay Composite, Method of Preparation and Use.
- 7. US 5,760,106 (June 2, 1998) Sealant Method of Epoxy Resin-Clay Composites.

08/20/2003 GHORDOF1 00000049 10039558

Entry of these documents into the application file is respectfully requested.

A check in the amount of \$180.00, the requisite fee for filing paper, is enclosed.

A copy of the submission is being served upon the attorney for the applicants in accordance with 37C.F.R. 1§.248.

Respectfully submitted,

Dated: Muguet 14 2003

Thomas Pinnavaia

Claytec, Inc



CERTIFICATE OF SERVICE

I hereby certify that a copy of the foregoing Third-Party Submission in Published

Application has been served upon the attorney by first-class mail, postage prepaid, this

14th Day of August, 2003, addressed as follows:

Charles E. Baxley Hart, Baxley, Daniels and Holton Fifth Floor 59 John St. New York, NY 10038 (US)

Thomas J. Pinnavaia

Claytec, Inc.